MilDef RW11



Rugged revolution

There are three important factors when considering rugged mobile computers; weight, ruggedness and performance – The MilDef RW11 series from MilDef excels in each area.

Building on the solid foundation of the Dual Core[™] MilDef RS11 and RV11, now comes the RW11, a 15.6" slim yet fully rugged mobile workstation enhancing the core design of the RV11, without sacrificing any of its rugged performance for military applications, the RW11 provides the most powerful Quad Core[™] performance in its class, and more. With main features such as an Intel[®] i7-3610QE CPU, Intel HD graphics 4000 (NVIDIA GeForce[®] GTX950M option available), up to 4x Raidable SATA SSD and up to 32GB RAM, the user will have all the performance required in a highly rugged and slim package.

Despite its low weight and size, the MilDef RW11 is designed for extreme environments and is made to be used in the field. MIL-STD-810G and IP65 certification is standard.

Guaranteed performance

Products supplied by MilDef, are always provided with lifetime support to ensure that the equipment maintains peak performance over many future missions.



MilDef RW11

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CPU RAM	Intel [®] Quad Core [™] i7-3610QE Processor Max 32 GB DDR3L 1600 MHz		
Graphics	Intel HD Graphics 4000		
Storage	Up to 4x SATA II/III SSD (removable)		
Disalau	Intel RAID 0, 1, 5, 10 Support		
Display	15.6" TFT LCD FHD (1920 x 1080), AG Glass, optical bonding, sunlight readable.		
Sound	HD Audio and stereo speakers		
	Embedded digital mic		
Keyboard/mouse	87-key LED backlit membrane keyboard with integrated numeric, Single resistive/Multi-touch capacitive touchpad		
Interfaces (right)	2 x SSD Bay (SATA II) 2 x USB 2.0		
(iigiit)	1 x GigaLAN RJ45		
Interfaces	2 x SSD Bay (SATA III)		
(left)	1 x USB 3.0 (1.5A fast charger)		
	1 x USB 3.0 1 x Microphone (Mini Jack)		
	1 x Audio output (Mini Jack)		
	1 x Line-in Jack (Mini Jack)		
Interfaces	1 x MIL DC in		
(rear)	1 x Display port		
	1 x VGA		
Internal ports	2 x Serial DB9 (Default: COM1,2) 3 x Mini PCIe full-size card		
	1 x Mini PCle full-size or half-size card		
	1 x USB 3.0		
	2 x USB 2.0		
Interfaces	1 x Multi bay port:		
(bottom)	- 1 x PCI-e - 1 x USB3.0		
	- 1 x USB 2.0		
	- 1 x Power (VBATA/1A & 5V/1A)		
Primary Battery	2 x Hot-Swap 10.8V / 5800mAh Li-Ion		
Power Input	AC Adapter 200W AC 100-240V 50/60Hz		
	MIL DC-in 19V		
	(MIL DC-in 12- 32V Optional)		
Case	CNC milled Aluminum (Colors available in black or green)		
Dimensions	392 x 302 x 42 mm (W x D x H)		
Dimensions	(with corner rubbers)		
Weight	4.86kg – Depending on configuration		
Other	1 x Replaceable cooling fan		
Certifications	CE, FCC, WEEE, REACH, IP65, MIL-STD-		
	810G* and MIL-STD-461F*, RoHS		
OS	Windows 7, 8.1, 10, Server 2012		
*Contact MilDef for full specif	fications of MIL-STD-810G and MIL-STD-461F		

MIL-STD-810G		
	Operating	Storage
Altitude Method 500.5, <i>(procedure I, II)</i>	4572 m (15000 ft)	12192 m (40000 ft)
Temperature Method 501.5 & 502.5, <i>(procedure I, II)</i>	-20 °C to 60 °C (-4 °F to 140 °F)	-40 °C to 70 °C (-40 °F to 158 °F)
Temp Shock Method 503.5 <i>(procedure I)</i>	-20 °C to 60 °C (-4 °F to 140 °F)	-
Shock Method 516.6, <i>(procedure I)</i>	40 G, 11 ms	40 G, 11 ms
Vibration Method 514.6, (<i>category 1, 14 & 20</i>) Rain Method 506.5, (<i>procedure II</i>)	M548 Tracked Vehicle, OH58A/C Helicopter and Composit wheeled vehicle vibration 276 kPa, 5 Surfaces, 40 min/Surface	-
Humidity	-	Ten 24 h test cycles
Method 507.5 Salt Fog		Salt 5 ±1 %, 24 h wet
Method 509.5, (procedure I)		+ 24 h dry/cycle. Total 2cycles / 96 h
Options		
Communications 2 nd LAN RJ45 (GigaLAN) Ublox Neo-M8N GPS/GLONASS		
	WLAN 802.11 ac/a/k	
Additional Connectivity	2 x Serial DB9 (Default: COM3,4) 1 x Mini HDMI 1 x Mini-Flex bay: (trade-off with 3rd-4th SSD) – Express Card (54mm)/PCMCIA – Others Signals include: - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/RX) - Power (+V3.3, +V5, +VBata, GND)	
	1 x Mini-Flex bay: (trade-off with 3rd~- - Express Card (54m - Others Signals incl - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V GND)	m)/PCMCIA ude: RX) 3.3, +V5, +VBata,
Display	1 x Mini-Flex bay: (trade-off with 3rd~- - Express Card (54m - Others Signals incl - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V	m)/PCMCIA ude: RX) 3.3, +V5, +VBata, een
Temperature	1 x Mini-Flex bay: (trade-off with 3rd ~ - Express Card (54m - Others Signals incl - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V GND) Capacitive touch scr 800 nits high brightr Operational Low Tem	m)/PCMCIA ude: XX) 3.3, +V5, +VBata, een less LCD perature: -30 °C
Temperature Graphic	1 x Mini-Flex bay: (trade-off with 3rd - Express Card (54m - Others Signals inclu- - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V GND) Capacitive touch scru 800 nits high brightr Operational Low Tem NVIDIA GeForce® GT add-on card*	m)/PCMCIA ude: 2X) 3.3, +V5, +VBata, een less LCD perature: -30 °C X950M 2GB discrete
Temperature Graphic Storage	1 x Mini-Flex bay: (trade-off with 3rd - Express Card (54m - Others Signals inclu- - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V GND) Capacitive touch scru 800 nits high brightr Operational Low Tem NVIDIA GeForce® GT add-on card*	m)/PCMCIA ude: 2X) 3.3, +V5, +VBata, 2een 1eess LCD perature: -30 °C X950M 2GB discrete 2000 Project
Temperature Graphic	1 x Mini-Flex bay: (trade-off with 3rd - Express Card (54m - Others Signals inclu- - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V GND) Capacitive touch scru 800 nits high brightr Operational Low Tem NVIDIA GeForce® GT add-on card* Optical drive by Cust (trade-off with 3rd, 4 TPM v1.2	m)/PCMCIA ude: 2X) 3.3, +V5, +VBata, een less LCD perature: -30 °C X950M 2GB discrete com Design Project th SSD + 2 nd Battery)
Temperature Graphic Storage	1 x Mini-Flex bay: (trade-off with 3rd - Express Card (54m - Others Signals inclu- - 1 x PCI-e - 1 x GLAN - 1 x USB2.0 - COM (TX/F - Power (+V GND) Capacitive touch scru 800 nits high brightr Operational Low Tem NVIDIA GeForce® GT add-on card*	m)/PCMCIA ude: 2X) 3.3, +V5, +VBata, een less LCD perature: -30 °C X950M 2GB discrete com Design Project th SSD + 2 nd Battery)



ISO 9001: Certificate No. FM68727 ISO 14001: Certificate No. EMS554313